

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of  
PENDSE et al.

Application No.: 09/802,664

Filed: March 9, 2001

Title: **Flip chip interconnection  
structure**

Examiner: Leonardo Andujar

Group Art Unit: 2826

Date: June 28, 2002

**Certificate of Mailing**

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June 28, 2002.

Linda Shaw

Date

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**TRANSMITTAL LETTER**

Commissioner of Patents  
Washington, D.C. 20231

Dear Sir:

In response to the Office Action mailed May 31, 2002 (Restriction Requirement),  
enclosed please find:

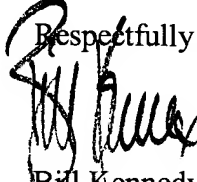
- [X] Preliminary Amendment and Response to Restriction Requirement;
- [X] Information Disclosure Statement (in duplicate);
- [X] PTO-1449 (PTO/SB/08A) form and copies of twenty (20) cited references.

Attorney Docket No.: CPAC 1003-1 US  
USSN: 09/802,664

PATENT

The Commissioner is hereby authorized to charge any additional fees that may be required by this paper, and to credit any overpayment, to Deposit Account No. 50-0869 (Docket No. CPAC 1003-1US). A duplicate of this paper is enclosed.

Respectfully submitted,



Reg. No. 33,407

Bill Kennedy

Registration No. 33,407

Date: June 28, 2002

HAYNES BEFFEL & WOLFELD LLP  
P.O. Box 366  
Half Moon Bay, CA 94019  
(650) 712-0340

Atty. Docket No. CPAC.1003-1  
Appl. No. 09/802,664



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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Rajendra D. PENDSE

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Signed

Linda Shaw

COMMISSIONER OF PATENTS  
WASHINGTON, D.C. 20231

PRELIMINARY AMENDMENT AND  
RESPONSE TO RESTRICTION REQUIREMENT

Dear Sir:

PRELIMINARY AMENDMENT

In the claims:

Please amend claims 12 - 17 as shown in the attached "Attachment under Rule 1.121", as follows:

a<sup>1</sup>  
12. The flip chip interconnection structure of claim 10 wherein the deformable material of the first member comprises gold.

13. The flip chip interconnection structure of claim 10 wherein the second member comprises a surface pad.

14. The flip chip interconnection structure of claim 10 wherein the second member comprises a lead.

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